SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG240320S26A-N-A0

Doc.Version:02

Customer Approval:	
Accept	☐ Reject

YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	福艺辑	2015,212
Check	Mechanical Engineer	刘振荣	2015.2.12
Verify		套上载	2015.5.12
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☐ APPROVAL FOR SPECIFICATIONS ONLY

■ APPROVAL FOR SPECIFICATIONS AND SAMPLE

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1. Revision History

Sample Version	DOC. Version	DATE		CHANGED BY	
A0	00	2014-12-17	SPEC ONLY	First issue	Fanny / Yang
A0	01	2014-12-19	SPEC ONLY	1. Modify LCM drawingP.5 2. Modify LED Lifetime TYP ValueP.14	Fanny / Yang
A0	02	2015-02-12	FULL SPEC	First Sample	Fanny / Ujl



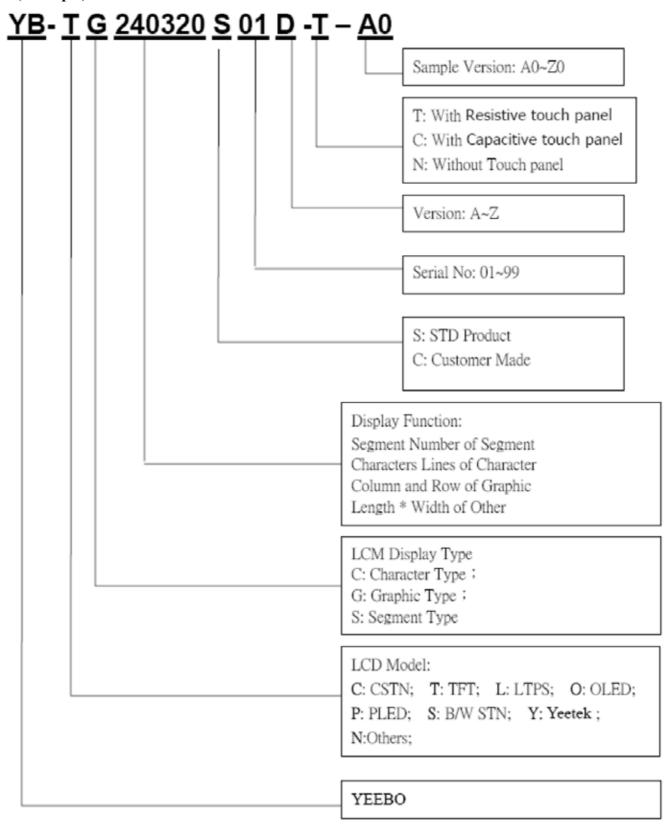
2. Table of Contents:

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3. Module Numbering System:

(Example)



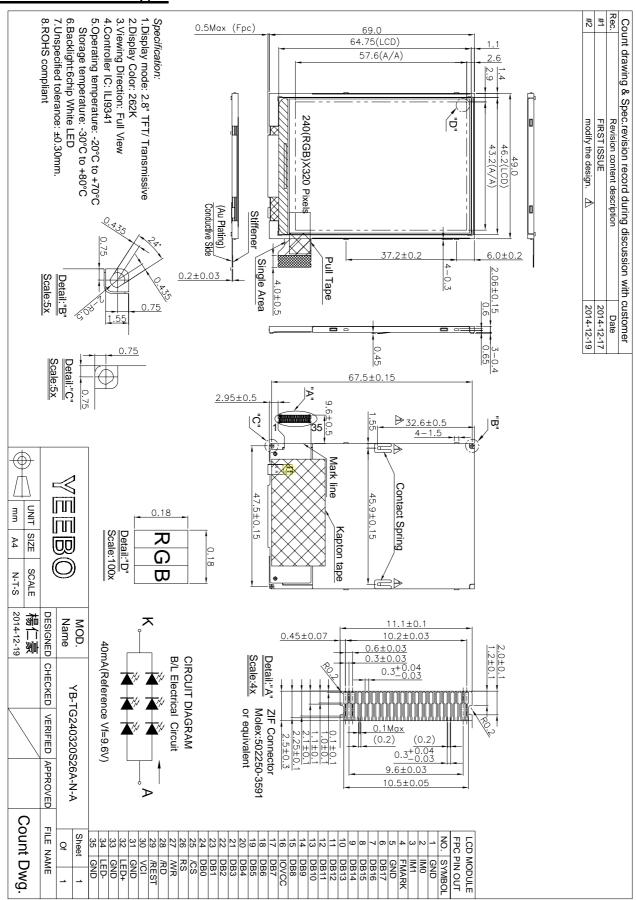


4. General Specification:

ITEM	CONTENTS
Module Size	49.0 (W) * 69.0 (H) * 2.06 (T) mm
Module Size(With FPC)	58.6 (W) * 69.5 (H) * 2.06 (T) mm
Display Size(Diagonal)	2.8 inch
Display Format	240(RGB)*320 Pixels
Active Area	43.2(W) * 57.6 (H) mm
Pixel Pitch	0.18* 0.18 mm
LCD Type	TFT (262K) / Transmissive / Normally Black
View Direction	Free
Controller IC	ILI9341
Weight	13.6g



5. LCM drawing:





6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Supply Voltage	V_{CI}	-0.3	ı	+4.6	Volt	Note1
Supply Voltage(Logic)	IOV_{CC}	-0.3	-	+4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70		-
Storage Temperature	Tstg	-30	-	+80		-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions

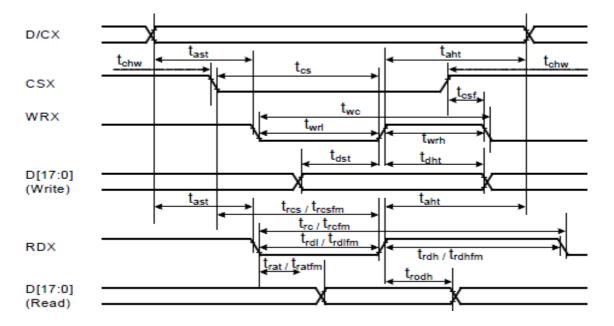
(Ta=25°C)

1 0					`	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply voltage	V_{CI}	-	2.6	2.8	3.0	Volt
Supply voltage for I/O	IOV _{CC}	1	1.65	2.8	3.0	Volt
Input Voltage	V_{IH}	1	0.7 * IOV _{CC}	1	IOV _{CC}	V
input voitage	$V_{ m IL}$	-	Vss	ı	0.3* IOV _{CC}	V
Power Supply Current for LCM	Icc	V _{CI} =2.8V	-	15.6	23.4	mA



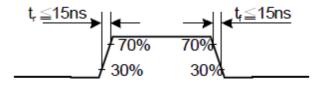
6-3 Timing Characteristics

6-3.1 Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080- $\rm II$ system)



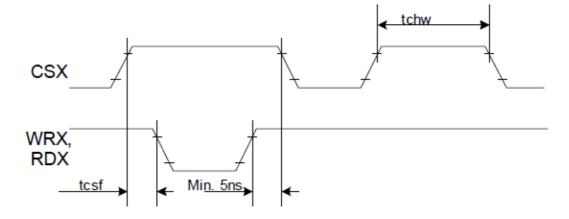
Signal	Symbo	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	tresfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D(47-0)	tdst	Write data setup time	10	-	ns	
D[17:0],	tdht	Write data hold time	10	-	ns	For maximum CL=30pF
D[17:10]&D[8:1], D[17:10],	trat	Read access time	-	40	ns	For minimum CL=30PF
D[17:10], D[17:9]	tratfm	Read access time	-	340	ns	For minimum CL-ope
D[17.8]	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.



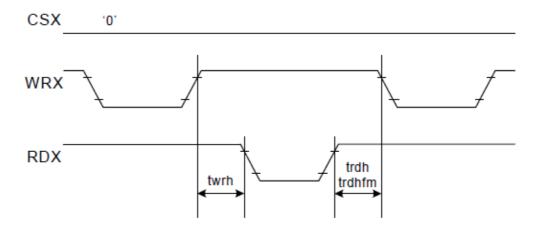


CSX timings:



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



7. Optical Characteristics:

Item		Crombal	Conditions	Spe	cificat	ions	Unit	Note
Item		Symbol	Conditions	Min	Тур	Max	Unit	Note
	Transmittance (With PL)		-	-	3.9	-	-	-
Contrast Ratio		CR	=0 Normal Viewing angle	-	800	-		(1)(2)
Response	time	TR+TF	-	-	30	-	ms	(1)(3)
	Hor	Θx+		-	80	-		
Viewing	1101	Өх-	CR 10	-	80	-	deg.	
angle	Vor	Өу+	CK 10	-	80	-	ueg.	-
	Ver			-	80	-		

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

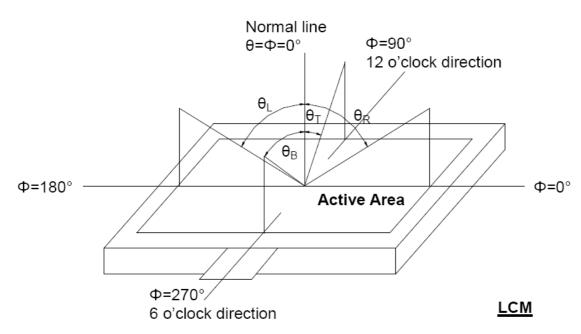
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.	Brightness
	D 1	X		0.5801	0.6301	0.6801	60 cd/m ²
	Red	у	$\theta = \phi = 0$ °	0.2825	0.3325	0.3825	
Chromaticity Coordinates (Transmissive)	Green	X	LED Backlight Color Degree x=TBD	0.2668	0.3168	0.3668	250 cd/m ²
		у		0.5660	0.6160	0.6660	
	Blue	X	y=TBD	0.0948	0.1448	0.1948	20 cd/m ²
		y		0.0187	0.0687	0.1187	20 cd/m²
	White	X	$= 7500 \text{ cd/m}^2$	0.2396	0.2896	0.3396	350 cd/m ²
		у	7500 cu /III	0.2574	0.3074	0.3574	550 CQ/III ²



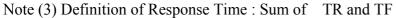
Note (1) Definition of Viewing Angle:

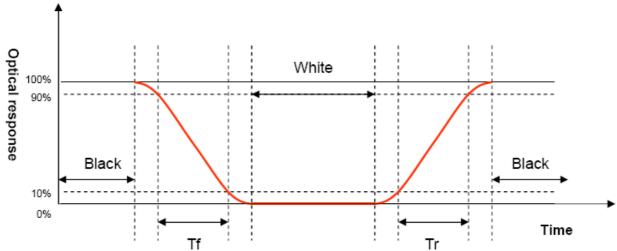


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black







8. Interface Pin Assignment:

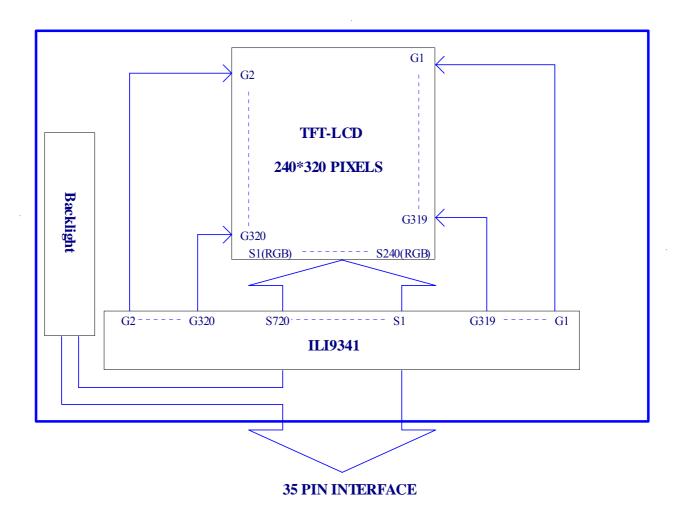
No.	Symbol		Function				
1	GND	Gro	und				
		Sele	ect M	IPU I	nterface mode		
2	IM0		18.44	11.40	MOLL Interfere Mede	DB Pin	n in use
_			IM1	IM0	MCU-Interface Mode	Register/content	GRAM
			0	0	80 MCU 16-bit bus interface II	D[8:1]	D[17:10],D[8:1]
			0	1	80 MCU 8-bit bus interface II	D[17:10]	D[17:10]
3	IM1		1	0	80 MCU 18-bit bus interface II	D[8:1]	D[17:0]
			1	1	80 MCU 9-bit bus interface II	D[17:10]	D[17:9]
4	FMARK	Frar	ne h	ead _l	pulse signal (leave it O	pen if not used)	
5	GND	Gro	und				
6	DB17	Data	a bus	6			
7	DB16	Data	a bus	6			
8	DB15	Data	a bus	6			
9	DB14	Data	a bus	5			
10	DB13	Data	a bus	5			
11	DB12	Data	a bus	6			
12	DB11	Data	a bus	5			
13	DB10	Data	a bus	5			
14	DB9	Data	a bus	6			
15	DB8	Data	a bus	5			
16	IOVCC	Digit	tal p	ower	supply		
17	DB7	Data	Data bus				
18	DB6	Data	Data bus				
19	DB5	Data	Data bus				
20	DB4	Data	Data bus				
21	DB3	Data	Data bus				
22	DB2	Data	a bus	5			



23	DB1	Data bus
24	DB0	Data bus
25	/CS	Chip select signal active low
26	RS	Display data(RS=H) / Command selection(RS=L)
27	/WR	Write signal active low
28	/RD	Read signal active low
29	/RESET	Reset signal active low
30	VCI	Analog power supply
31	GND	Ground
32	LED+	LED power supply(+)
33	GND	Ground
34	LED-	LED power supply(-)
35	GND	Ground



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

 $(Ta=25^{\circ}C)$

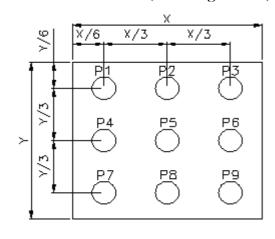
7. Dani 100di EED Backiigitt.						• = 5 0)	
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	ı	40	ı	mA	V=9.6V	
Supply Voltage	V	9.0	9.6	10.2	V	If=40mA	
Reverse Voltage	VR	-	-	TBD	V	-	
Luminous Intensity for LCM	IV	280	350	-	Cd/m ²		2
Uniformity for LCM	-	70	-	-	%	If=40mA	3
Life Time	-	-	50000	-	Hr.		4
Color	White						

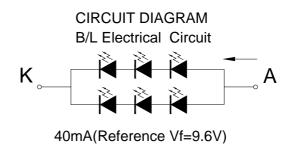
NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram





(Effective spatial Distribution)

Hole Diameter ø3 mm; 1 to 9 per Position Measured Luminous



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.	
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: $\pm 4KV$ 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5 $^{\circ}$ C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E.General Inspection Level

 take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

- a. Non-conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

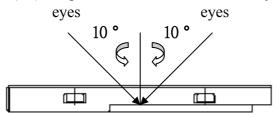
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

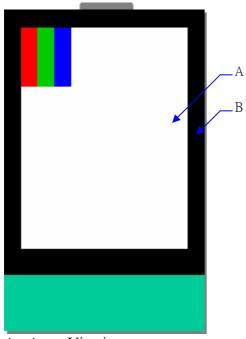


12-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
- (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at $30\pm5cm$.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)
- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 				2.5
03	LCD and Touch Panel black spots, white spots,		ensely spaced:	Size(mm) $Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ \le 0.30$ 0.30 < Φ No more than two	Acceptable Q'ty Accept no dense 2 2 1 0 spots within 3mm.	2.5
	contamination (non – display)	3.2 Line type: (As for the state of the stat	Length(mm) $$ $L \leq 3.0$ $L \leq 2.5$ $$	$\begin{array}{c} \text{Width(mm)} \\ \text{W} \! \leq \! 0.02 \\ \\ 0.02 \! < \! \text{W} \! \leq \! 0.05 \\ \\ 0.03 \! < \! \text{W} \! \leq \! 0.08 \\ \\ 0.08 \! < \! \text{W} \end{array}$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5



NO	Item	Criterion		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5	
05	Scratches	Follow NO.3 -2 Line Type.		
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:	2.5	



NO	Item	Criterion				
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:				
		y: Chip width x: Chip length z: Chip thickness				
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$				
07	Glass crack	Non-conductive portion:	2.5			
		y: Chip width x: Chip length z: Chip thickness				
		$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$				
		 ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y ≤ 1/3L X ≤ a 				



NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion				
NO 14	Touch Panel Chipped glass	z : Chip thickness $Z \le t$ \odot Unit: mm	y: Chip width z: t: Touch Panel Total t	x: Chip length x≤1/8a	side	AQL 2.5
		z : Chip thickness $z \le t$ • Unit: mm	y: Chip width ≤ 1/2 k and not over viewing area ore chips, x is the total in the second state of the se	x: Chip length x≤1/8a length of each chip		



NO	Item	Criterion	AQL	
15	Touch Panel(Fish eye, dent and bubble on film)	$ \begin{array}{ c c c } \hline SIZE(mm) & Acceptable Q'ty \\ \hline \Phi \leq 0.2 & Accept no dense \\ \hline 0.2 < D \leq 0.4 & 5 \\ \hline 0.4 < D \leq 0.5 & 2 \\ \hline 0.5 < D & 0 \\ \hline \end{array} $	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.		
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.		
20	Definition of Pixel	Pixel: Group of Three Sub-pixels (Red, Green, Blue): Dot: Red or Green or Blue or or Dot: Any sub-pixel Bright Dot Defects Dots (sub-pixels) on display which is bright in the picture and visible at Black Pattern.		



Dark Dot Defects

Dots(sub-pixels) on display which is dark in the picture and visible at Red/Green/Black/White Pattern.

Neighbour Dot Defects

Two or three neighbour dots (dot: sub-pixel) cluster(R&G,G&B,B&R,or R&G&B).Dot Defects Inspection Criteria

NOTE: Dot out of VA can be ignored.

- 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1					
Items	Inspection Criteria				
	Details	Allowed quantity			
Bright Dot	Not Neighbour Dot	2			
Dark Dot	Not Neighbour Dot	3			
Total acceptable Qty		5			

Size of dot defect is larger than half of one sub-pixel.

13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10 , and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10 and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.